

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2 θ 1/2
KM-27ID-08	HIGH EFFICIENCY RED (GaAsP/GaP)	RED DIFFUSED	7	30	40°

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

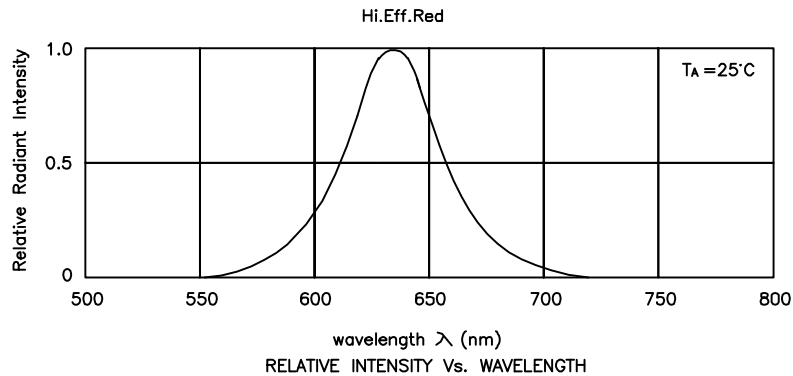
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	High Efficiency Red	627		nm	I _F =20mA
λ_D	Dominant Wavelength	High Efficiency Red	625		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	High Efficiency Red	45		nm	I _F =20mA
C	Capacitance	High Efficiency Red	15		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	High Efficiency Red	2.0	2.5	V	I _F =20mA
I _R	Reverse Current	High Efficiency Red		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	High Efficiency Red	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	160	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

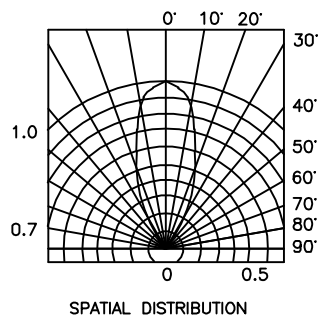
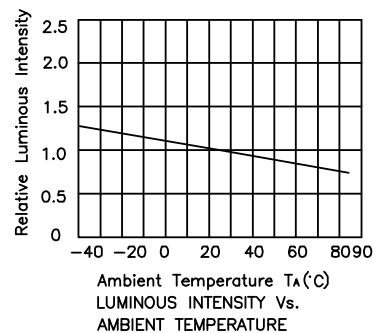
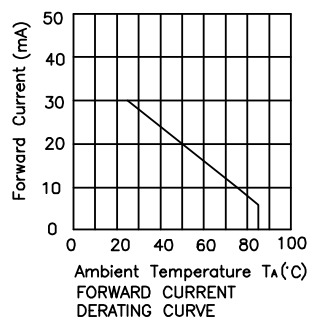
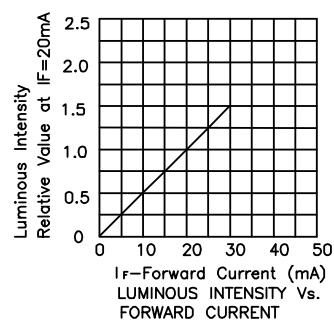
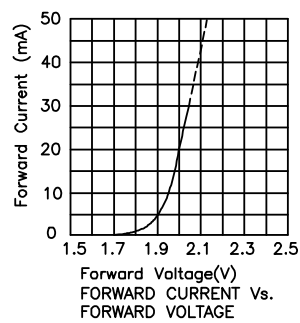
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



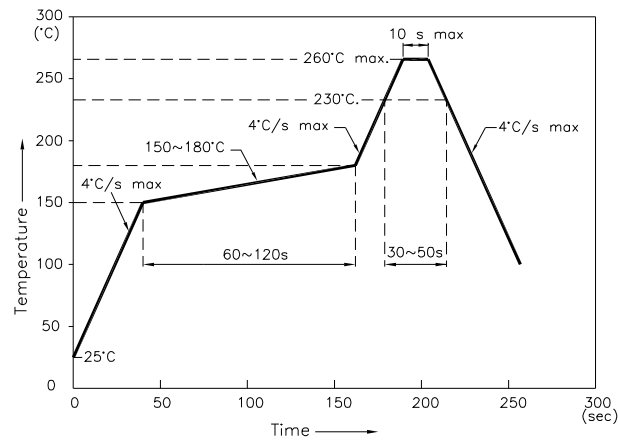
High Efficiency Red

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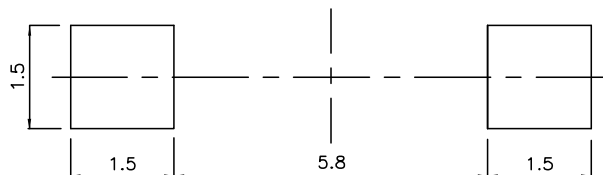
Reflow Soldering Profile For Lead-free SMT Process.



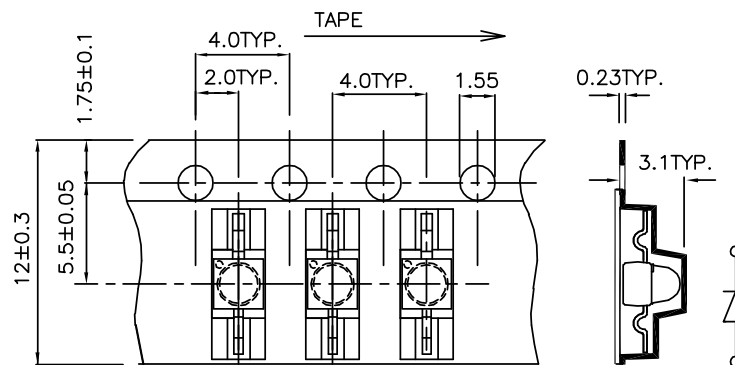
NOTES:

1. We recommend the reflow temperature $245^{\circ}\text{C} (+/-5^{\circ}\text{C})$. The maximum soldering temperature should be limited to 260°C .
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: $\pm 1\text{nm}$
2. Luminous Intensity: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.